IN THE CLAIMS:

Please amend claims 1-30 as provided below:

1. (Currently amended) An ~~O~~optoelectronic arrangement ~~having~~comprising:

[[-]] a printed circuit board, which defines a first [[y]] direction parallel to ~~the~~ a printed circuit board surface and a second [[z]] direction perpendicular to the printed circuit board surface,

[[-]] a first electrical contact-making region of the printed circuit board with a plurality of first contacts,

[[-]] a receptacle structure arranged on the printed circuit board and having a receptacle opening for receiving a pluggable optoelectronic module,

[[-]] a pluggable optoelectronic module,

[[-]] a second electrical contact-making region of the optoelectronic module with a plurality of second contacts, and

[[-]] plug-in means for plugging the optoelectronic module into the receptacle structure in such a way that, during the plug-in operation, the module is firstly introduced into the receptacle structure in the [[y]] first direction and is then lowered in the [[z]] second direction in the direction of the printed circuit board,

[[-]] wherein the second contacts of the optoelectronic module ~~being~~ are in electrical contact with the first contacts of the printed circuit board in the plugged-in position.

2. (Currently amended) The ~~A~~arrangement according to Claim 1, wherein the plug-in means ~~comprising~~ comprises a locking/unlocking mechanism formed on the module, by means of which mechanism the module ~~can be~~ is raised or lowered in the [[z]] second direction.

3. (Currently amended) The ~~A~~arrangement according to Claim 1, wherein the module ~~having~~ comprises a module housing with an end side, a rear side, a top side, an underside and two side walls, ~~it being possible for~~ and configured to receive at least one optical plug ~~to be plugged~~ into the module via the end side.

4. (Currently amended) The ~~A~~arrangement according to Claim[[s]] 2 ~~and 3~~, wherein the locking/unlocking mechanism ~~having~~ comprises a lever ~~with~~ configured to move between two end positions ~~that can be actuated from~~ at the end side of the module, the module being in a locked state with respect to the printed circuit board in one end position of the lever.

5. (Currently amended) The ~~A~~arrangement according to Claim 4, wherein the locking/unlocking mechanism ~~having~~ further comprises two arms acting as a lever, which are mounted in rotatable fashion at opposite side walls of the module housing in each case ~~in~~ at a bearing location.

6. (Currently amended) The ~~A~~arrangement according to Claim 5, wherein the arms, on the other side of the bearing location opposite the end side, in each case ~~being shaped in such a way that they~~ are configured to form at least two end regions at a different distance from the bearing location, wherein one of said arm end regions ~~coming into~~ contacts ~~with~~ the printed circuit board or the receptacle structure in one end position of the lever and the other of said arm end regions ~~coming into~~ contacts ~~with~~ the printed circuit board or the receptacle structure in the other end position of the lever.

7. (Currently amended) The ~~A~~arrangement according to Claim 6, wherein the arms each branch~~ing~~ at their ends ~~in each case~~ in Y-shaped fashion to form two sub-arms in such a way that one sub-arm is in contact with the printed circuit board or the receptacle structure in the one end position of the lever and the other sub-arm is in contact with the printed circuit board or the receptacle structure in the other end position of the lever.

8. (Currently amended) The ~~A~~arrangement according to Claim[[s]] 2 ~~and 3~~, wherein the locking/unlocking mechanism ~~having~~ comprises elements which protrude from at least one outer area of the module housing in the locked state of the module.

9. (Currently amended) The ~~A~~arrangement according to Claim 1, wherein the plug-in means ~~comprising~~ comprises guiding means which provide a guiding of the module in the receptacle structure during the movement of the module in the [[y]] first direction.

10. (Currently amended) The ~~A~~arrangement according to Claim 1, further comprising spring means ~~being provided, which~~ configured to press the plug-in module onto the printed circuit board with a spring force directed perpendicular to said printed circuit board surface.

11. (Currently amended) The ~~A~~arrangement according to Claim 10, wherein the spring means ~~being formed~~ resides on the receptacle structure.

12. (Currently amended) The ~~A~~arrangement according to Claim 1, for the positioning of the module in the [[y]] first direction, the module ~~forming~~ comprising first positively locking elements and the printed circuit board ~~forming~~ comprising second positively locking elements, ~~which~~ wherein the first and second positively locking elements intermesh when the module is plugged in.

13. (Currently amended) The ~~A~~arrangement according to Claim 12, the first positively locking elements of the module ~~being formed by~~ comprising at least two projecting pins and the second positively locking elements of the printed circuit board ~~being formed by~~ comprising correspondingly arranged holes.

14. (Currently amended) The ~~A~~arrangement according to Claim 1, further comprising a latching mechanism ~~being provided, which~~ configured to impede[[s]] the module[[s]] in the plugged-in position from moving in the [[z]] second direction away from the printed circuit board surface.

15. (Currently amended) The ~~A~~arrangement according to Claim 14, wherein the latching mechanism ~~having~~ comprises spring elements which latch with structures of the module during the plug-in operation after the lowering of the module in the [[z]] second direction.

16. (Currently amended) The ~~A~~arrangement according to Claim[[s]] ~~2 and~~ 14, wherein the locking/unlocking mechanism ~~deactivating~~ is configured to deactivate the latching mechanism when the module is raised in the [[z]] second direction.

17. (Currently amended) The ~~A~~arrangement according to Claim 1, wherein the second contacts of the module and the first contacts of the printed circuit board in each case ~~being~~ are arranged in the form of a two-dimensional matrix.

18. (Currently amended) The ~~A~~arrangement according to Claim 3, wherein the second electrical contact-making region of the optoelectronic module with the plurality of second contacts ~~being~~ is formed by a plug base arranged on the underside of the module housing.

19. (Currently amended) The ~~A~~arrangement according to Claim 18, wherein the second contacts arranged at the plug base ~~being~~ are formed in an elastically deformable fashion.

20. (Currently amended) The ~~A~~arrangement according to Claim 1, wherein some of the second contacts ~~being~~ are formed in a mechanically leading fashion, in such a way that a defined electrical contact-making order is provided during the plugging-in and during the removal of the module.

21. (Currently amended) The ~~A~~arrangement according to Claim 1, wherein the first electrical contact-making region of the printed circuit board ~~being~~ is formed directly on the surface of the printed circuit board, and the first contacts ~~being~~ are formed by metallizations directly on the surface of the printed circuit board.

22. (Currently amended) The ~~A~~arrangement according to Claim 1, further comprising a heat sink ~~additionally being provided, which~~ configured to project[[s]] into the receptacle structure via an opening at the top side of the receptacle structure and make[[s]] large-area mechanical contact with the module in the plugged-in position.

23. (Currently amended) The ~~A~~arrangement according to Claim 22, further comprising a spring means ~~additionally being provided, which~~ configured to press the heat sink against the plugged-in module with a spring force.

24. (Currently amended) The ~~A~~arrangement according to Claim 23, wherein the spring means ~~being~~ is supported at the receptacle structure and correspondingly additionally ~~pressing~~presses, in the plugged-in position of the module, the second electrical contact-making region of the module against the first electrical contact-making region of the printed circuit board.

25. (Currently amended) The ~~A~~arrangement according to Claim 24, wherein the spring means ~~having~~ comprises two side parts running parallel to one another and ~~which are~~ respectively connected to one side of the receptacle structure, and wherein the spring means further comprises at least two spring arms that are formed in resilient fashion and connect the side parts together, wherein the spring arms partly rest~~ing~~ on the heat sink and exert~~ing~~ a spring force on the heat sink in the [[z]] second direction.

26. (Currently amended) The ~~A~~arrangement according to Claim 1, wherein the receptacle structure ~~being formed by~~ comprises a shielding cage comprising an electrically conductive material.

27. (Currently amended) The ~~A~~arrangement according to Claim 26, wherein the shielding cage ~~having~~ comprises at its underside a plurality of protruding pins via which the shielding cage is mechanically fixedly connected to the printed circuit board.

28. (Currently amended) The ~~A~~arrangement according to Claim 27, wherein the shielding cage ~~being~~ is electrically connected to a shielding potential of the arrangement via the protruding pins.

29. (Currently amended) The ~~A~~arrangement according to Claim 26, wherein the printed circuit board ~~having~~ comprises a metallization on the printed circuit board surface in the region covered by the shielding cage and~~, except for in~~ having a cut-out portion therein corresponding to the first electrical contact-making region, at its top side.

30. (Currently amended) The ~~A~~arrangement according to Claim 1, wherein the module ~~being formed as~~ comprises a parallel optoelectronic module via which data can be emitted or received in parallel on a plurality of optical channels.